

Notification# 20190626002.0
Datasheet for SN74LVC1G08-Q1
Information Only

Date: August 15, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services


Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC1G08QDBVRQ1	null
SN74LVC1G08QDCKRQ1	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190626002.0	PCN Date:	Aug. 15, 2019
Title:	Datasheet for SN74LVC1G08-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
Notification Details			
Description of Change:			
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>			
		SN74LVC1G08-Q1 <small>SCES556G – MARCH 2004 – REVISED JUNE 2019</small>	
Changes from Revision F (April 2008) to Revision G			
			Page
•	Changed data sheet to new TI format		1
•	Added DRY package to <i>Device Information</i> table.		1
•	Added <i>Thermal Information</i> table.		5
•	Added <i>Typical Characteristics</i>		7
•	Added <i>Detailed Description</i> section.		10
•	Added <i>Application and Implementation</i> section.		11
•	Added <i>Power Supply Recommendations</i> section.		12
•	Added <i>Layout</i> section.		12
The datasheet number will be changing.			
Device Family	Change From:	Change To:	
SN74LVC1G08-Q1	SCES556F	SCES556G	
These changes may be reviewed at the datasheet links provided.			
http://www.ti.com/product/SN74LVC1G08-Q1			
Reason for Change:			
To accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
PCLVC1G08QDRYRQ1	SN74LVC1G08IDCKRQ1	SN74LVC1G08QDBVRQ1	SN74LVC1G08QDCKRQ1
SN74LVC1G08QDRYRQ1			

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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